ABSTRACT

A process for forming bumps on electrode pads for a wiring board including a substrate and a plurality of electrode pads. The process (a) forms a laminated two-layer film on the wiring board and forms a pattern of apertures at positions corresponding to the electrode pads, the laminated two-layer film including a lower layer containing an alkali-soluble radiation-nonsensitive resin composition and an upper layer containing a negative radiation-sensitive resin composition; (b) fills a low-melting metal in the aperture pattern; (c) reflows the low-melting metal by pressing or heating to form bumps; and (d) peels and removes the laminated two-layer film from the board. The laminated film including two layers with different properties permits high resolution and easy peeling.